

TOSHIBA InGaAlP LED

TLRE53T,TLRME53T,TLSE53T,TLOE53T,LYE53T, TLPYE53T,TLGE53T,TLFGE53T,TLPGE53T

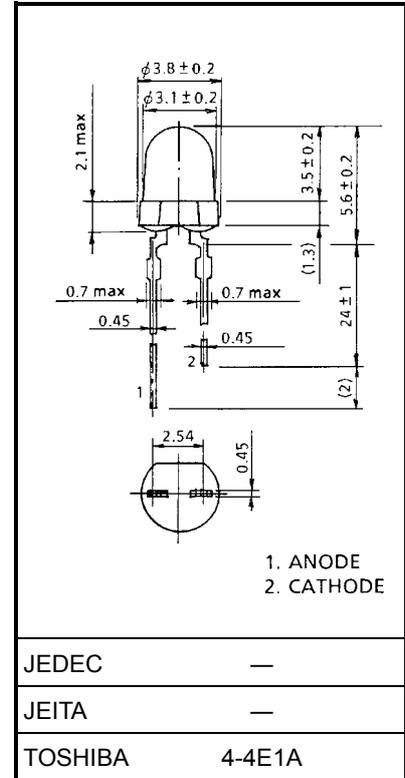
Panel Circuit Indicators

- $\phi 3$ mm package
- InGaAlP technology
- All plastic mold
- Transparent lens
- Line-up: 6 colors (red, orange, yellow, pure yellow, green and pure green)
- High intensity light emission
- Excellent low current light output
- Applications: message boards, security devices and dashboard displays

Line-up

Product Name	Color	Material
TLRE53T	Red	InGaAlP
TLRME53T	Red	
TLSE53T	Red	
TLOE53T	Orange	
TYE53T	Yellow	
TLPYE53T	Pure Yellow	
TLGE53T	Green	
TLFGE53T	Green	
TLPGE53T	Pure Green	

Unit: mm



Weight: 0.14 g

Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA)	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operating Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLRE53T	50	4	120	-40~100	-40~120
TLRME53T	50	4	120		
TLSE53T	50	4	120		
TLOE53T	50	4	120		
TLYE53T	50	4	120		
TLPYE53T	50	4	120		
TLGE53T	50	4	120		
TLFGE53T	50	4	120		
TLPGE53T	50	4	120		

Electrical and Optical Characteristics (Ta = 25°C)

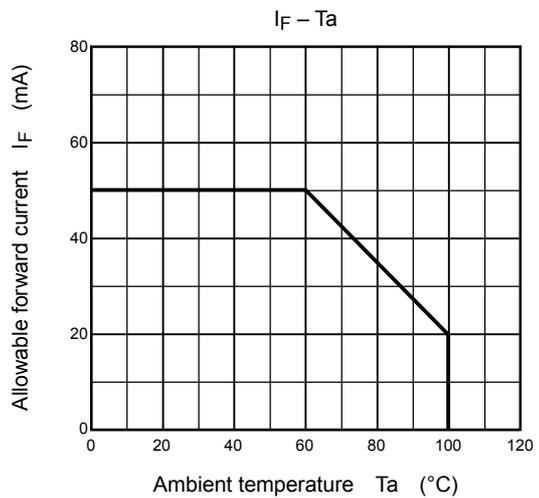
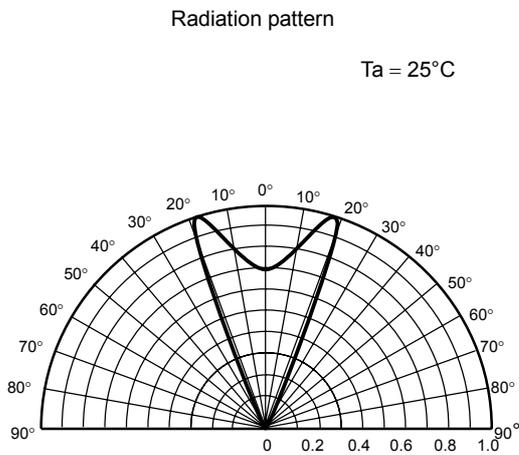
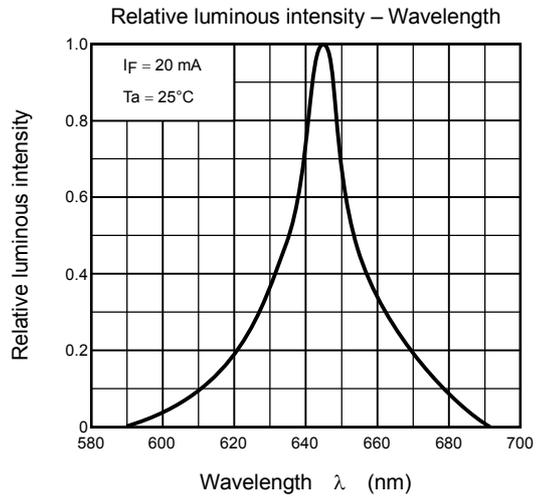
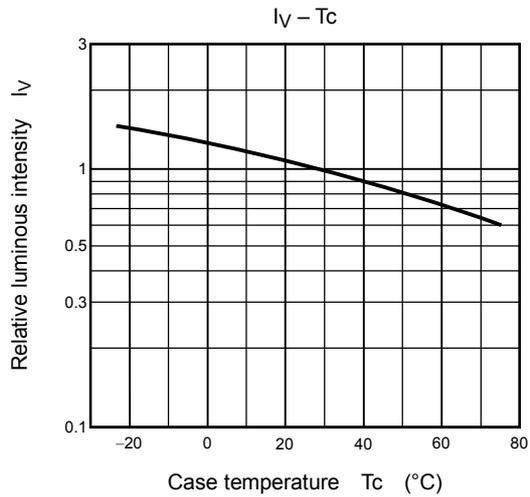
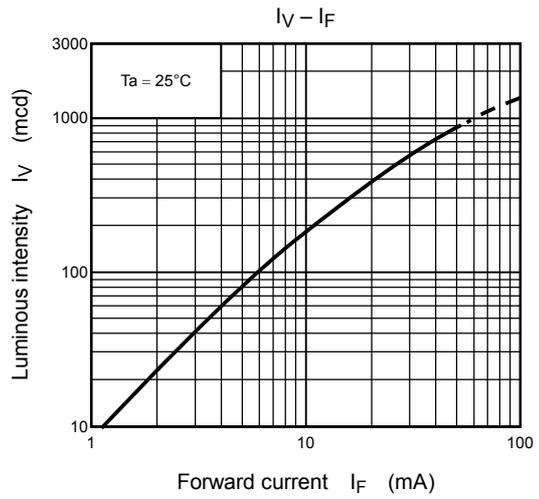
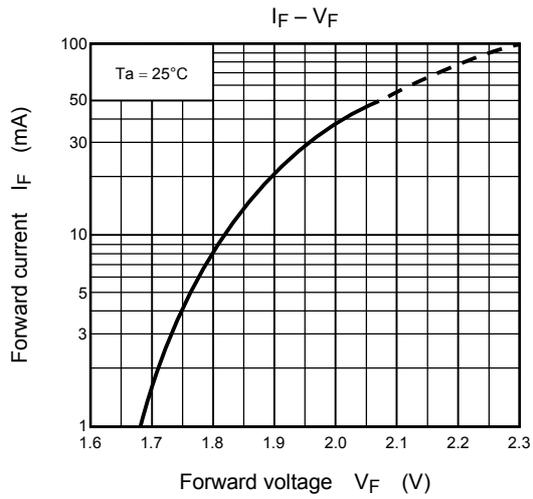
Product Name	Typ. Emission Wavelength				Luminous Intensity I _V			Forward Voltage V _F			Reverse Current I _R	
	λ _d	λ _p	Δλ	I _F	Min	Typ.	I _F	Typ.	Max	I _F	Max	V _R
TLRE53T	630	(644)	20	20	153	400	20	1.9	2.4	20	50	4
TLRME53T	626	(636)	23	20	272	600	20	1.9	2.4	20	50	4
TLSE53T	613	(623)	20	20	272	800	20	1.9	2.4	20	50	4
TLOE53T	605	(612)	20	20	272	1000	20	2.0	2.4	20	50	4
TLYE53T	587	(590)	17	20	272	800	20	2.0	2.4	20	50	4
TLPYE53T	580	(583)	14	20	153	450	20	2.0	2.4	20	50	4
TLGE53T	571	(574)	17	20	153	400	20	2.0	2.4	20	50	4
TLFGE53T	565	(568)	15	20	85	200	20	2.0	2.4	20	50	4
TLPGE53T	558	(562)	14	20	47.6	130	20	2.1	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

Precautions

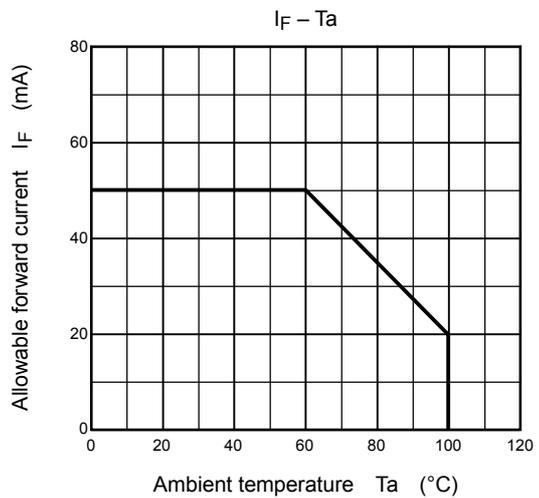
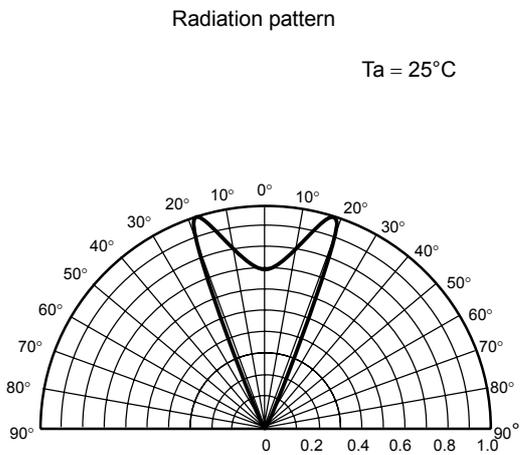
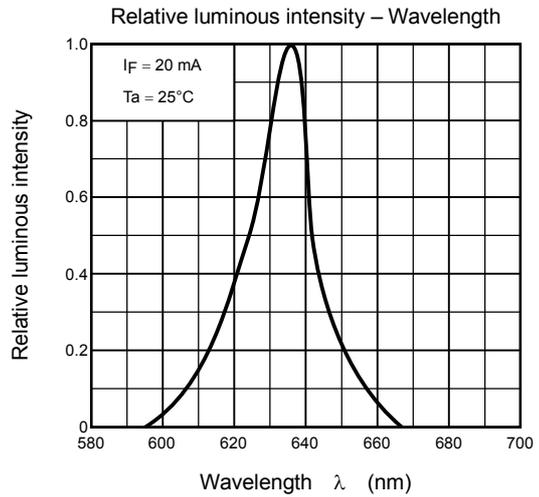
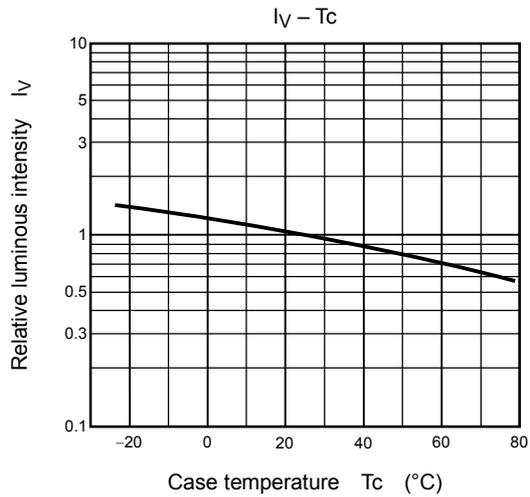
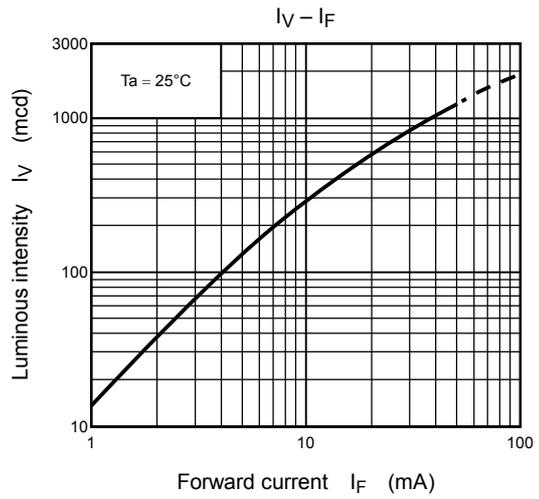
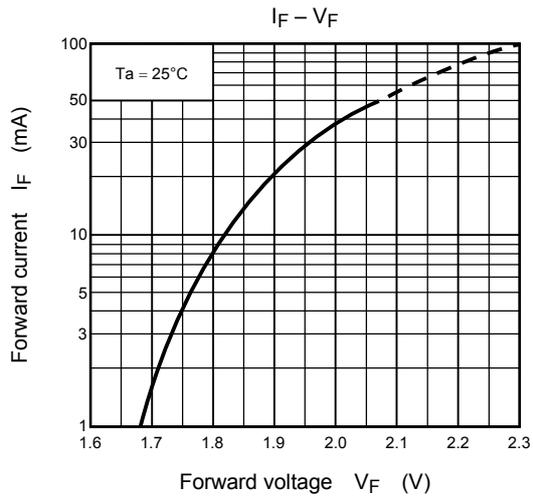
Please be careful of the following:

- Soldering temperature: 260°C max, soldering time: 3 s max
(soldering portion of lead: up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

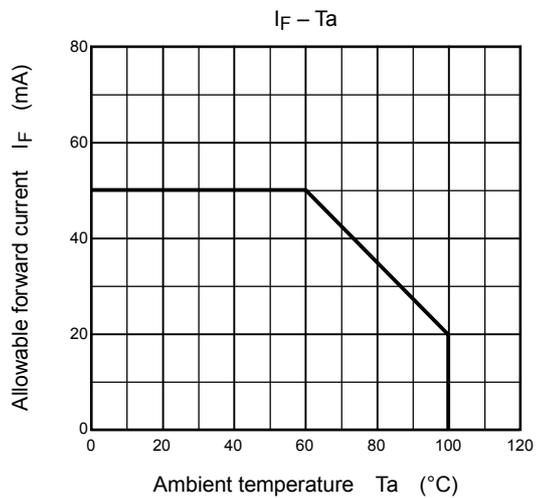
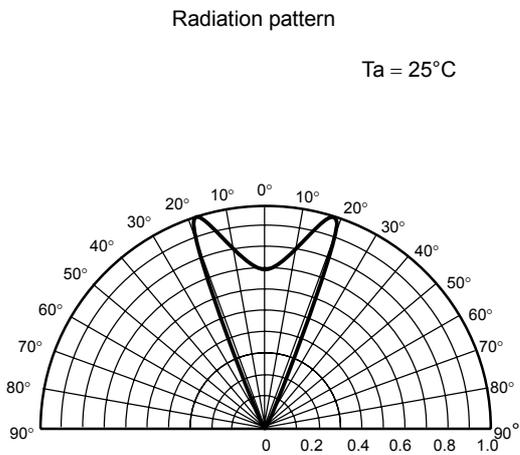
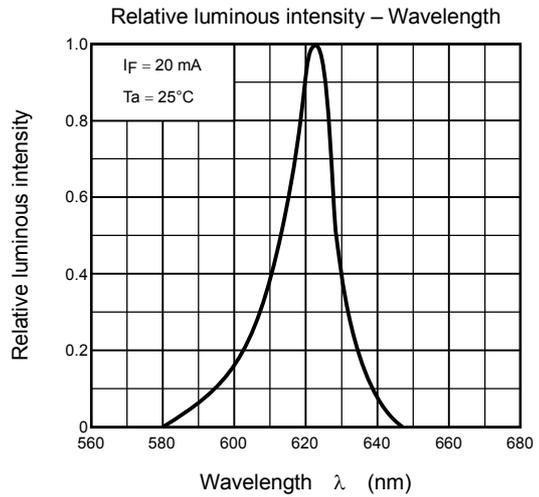
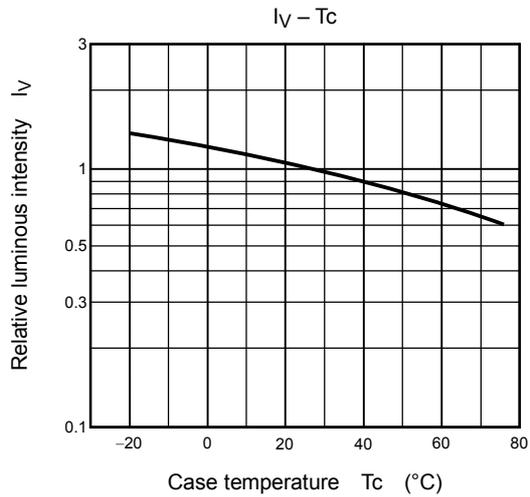
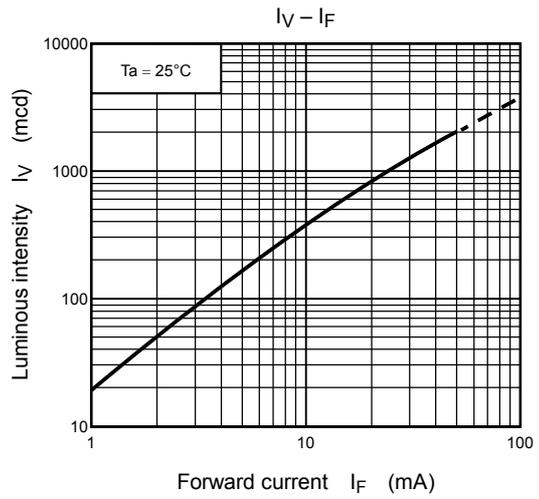
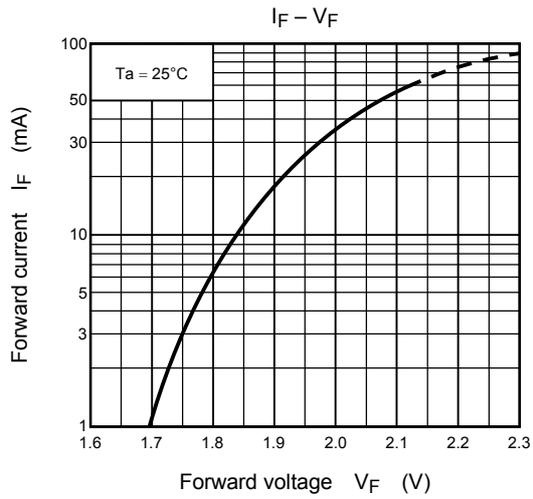
TLRE53T



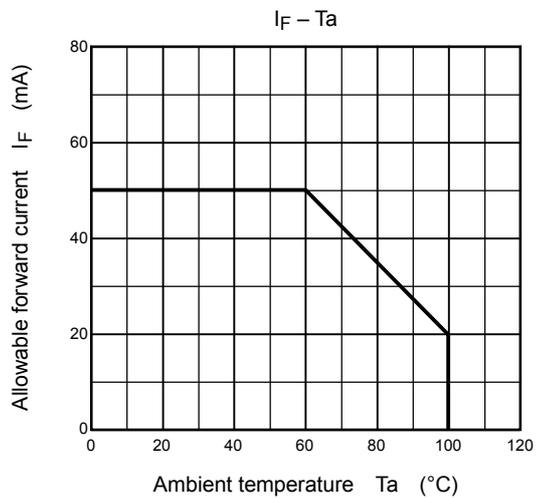
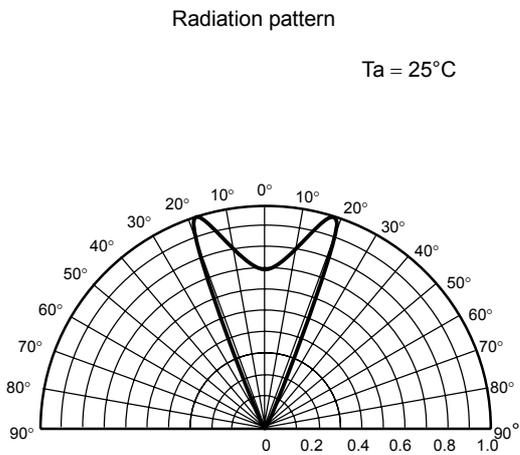
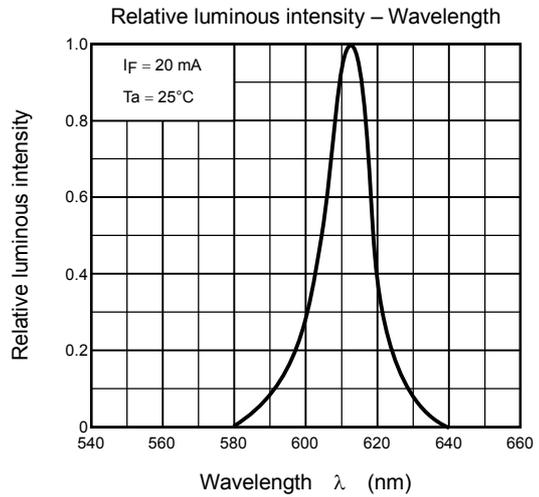
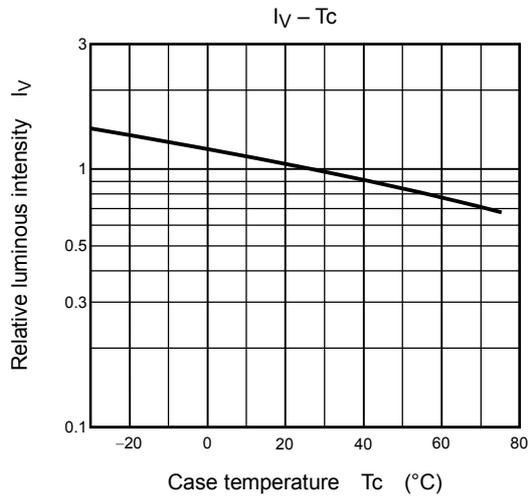
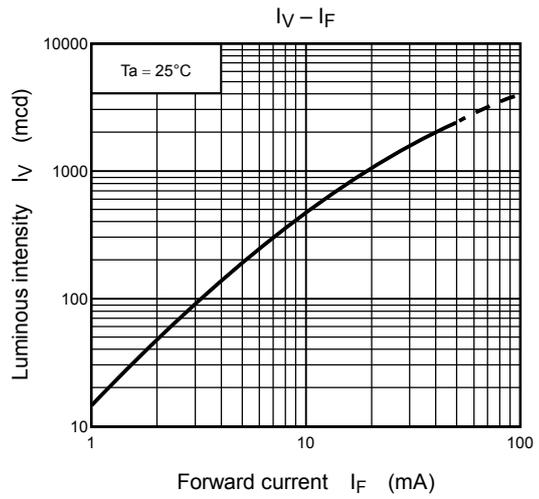
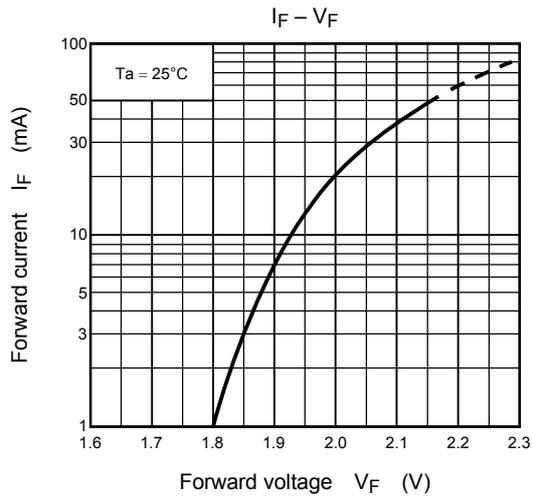
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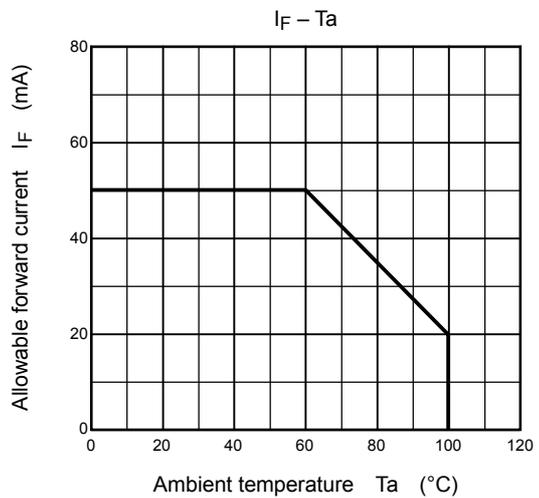
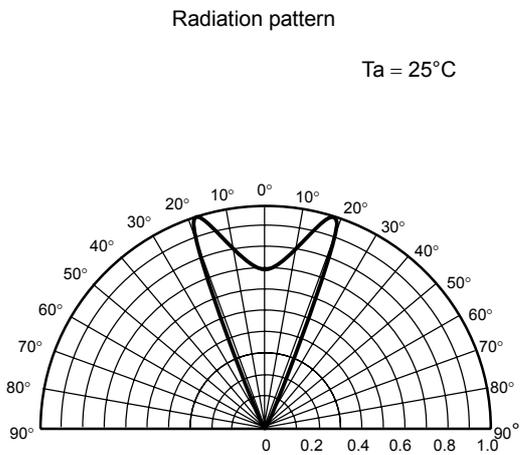
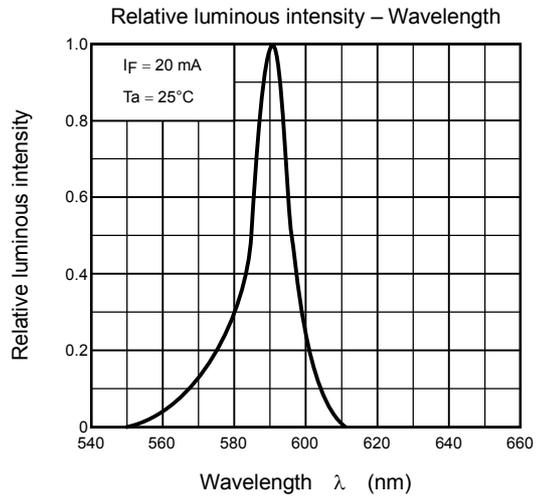
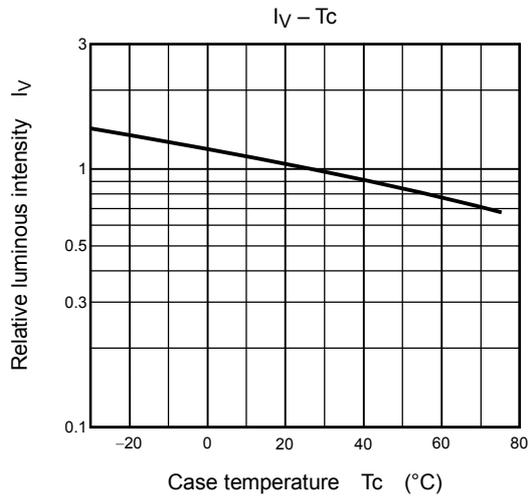
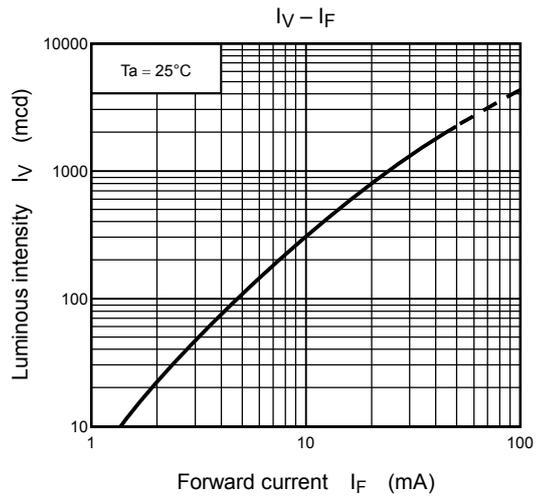
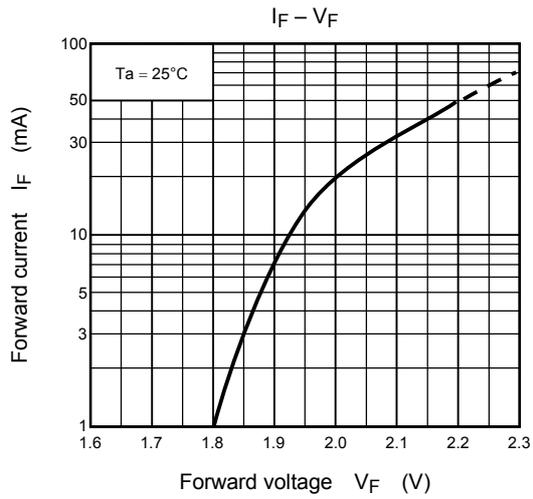
TLSE53T



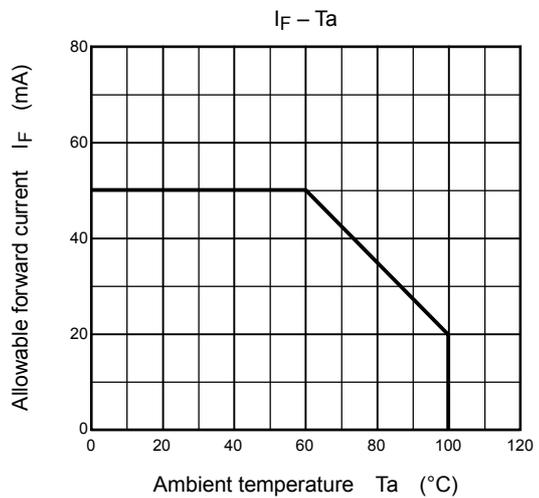
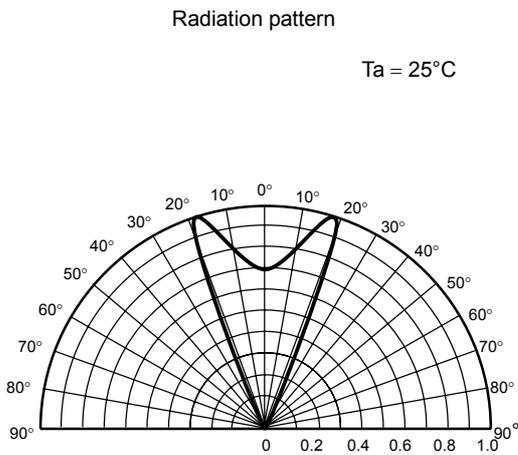
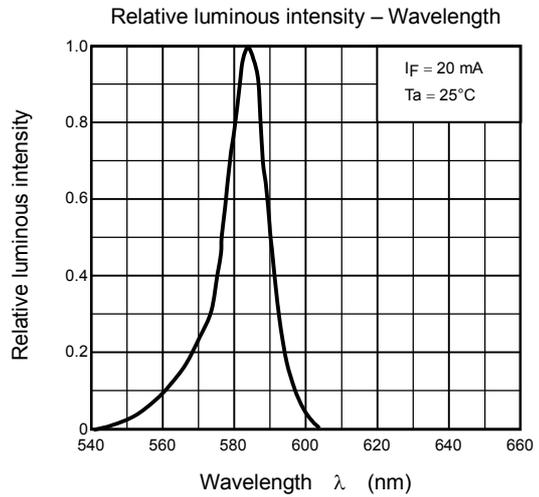
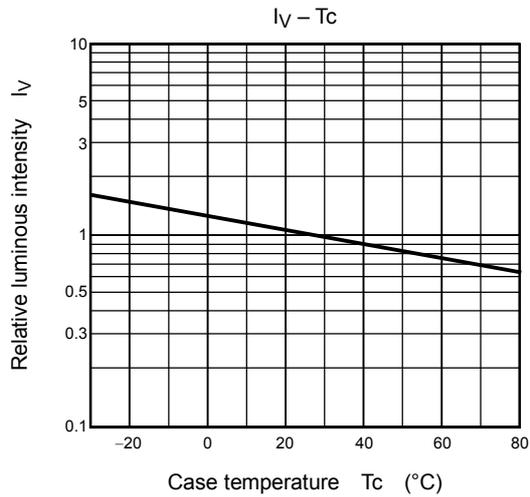
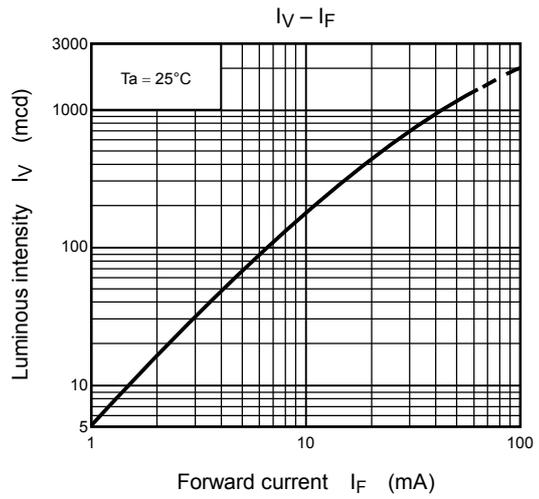
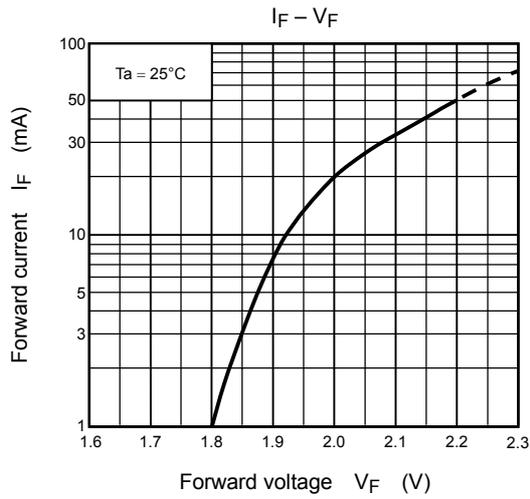
TLOE53T



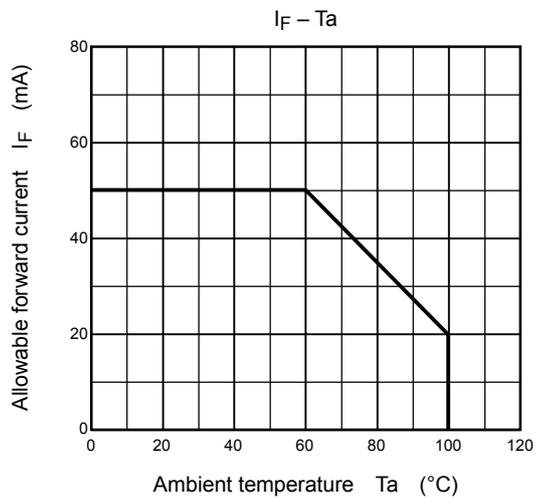
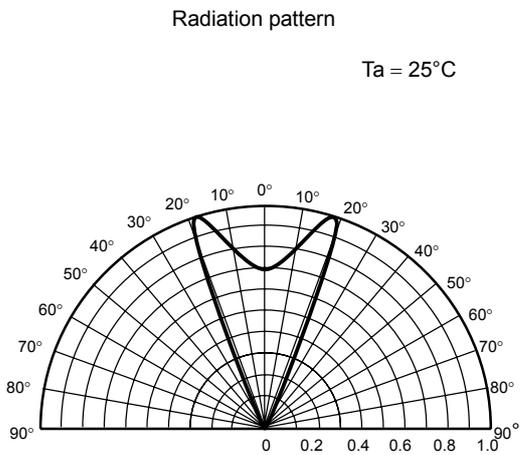
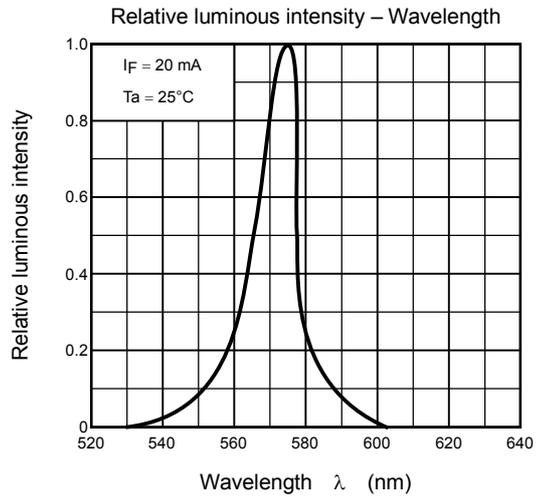
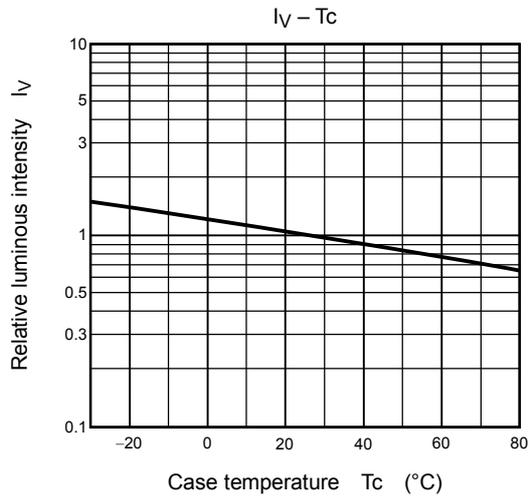
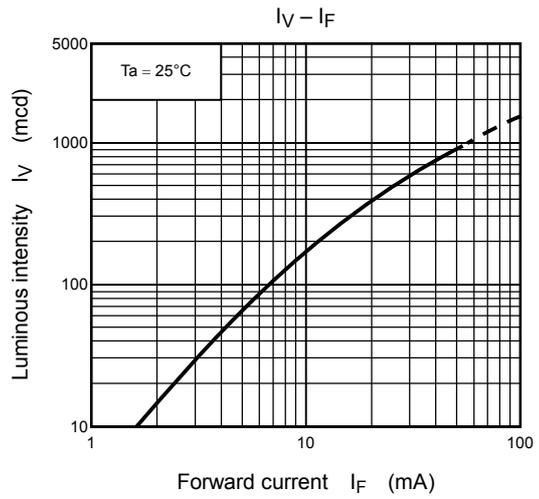
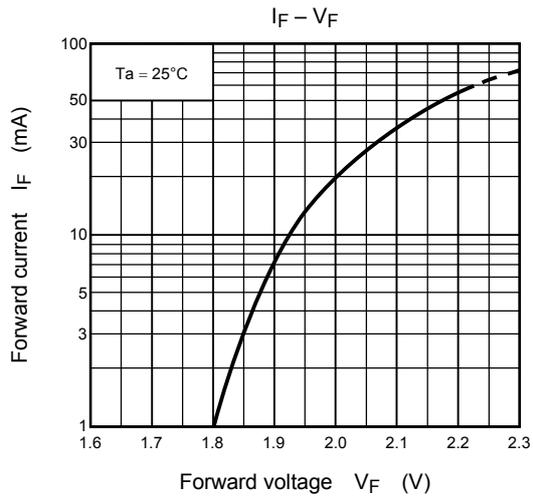
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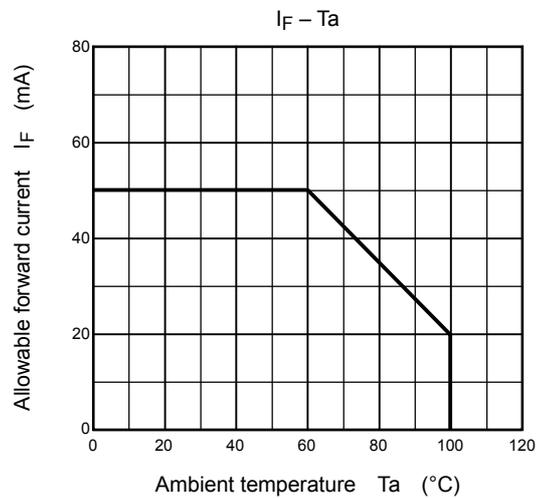
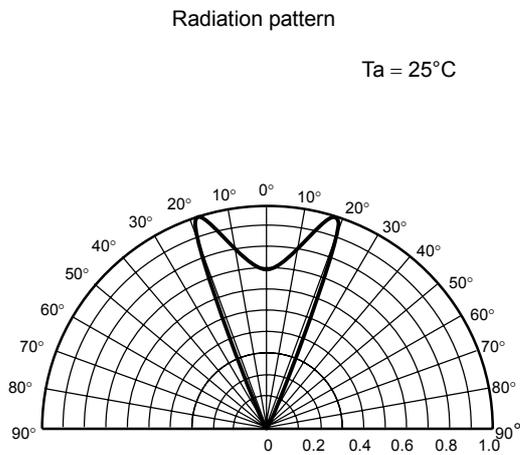
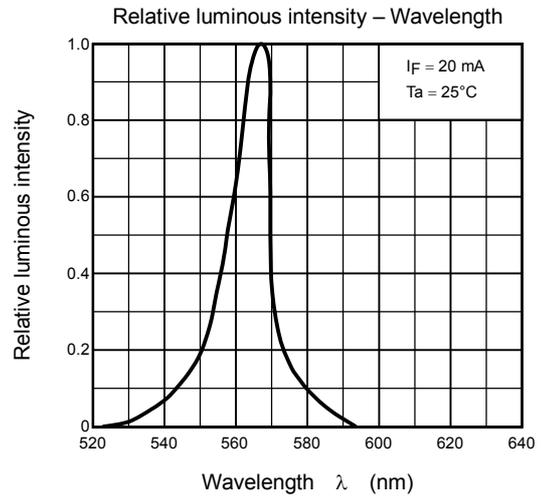
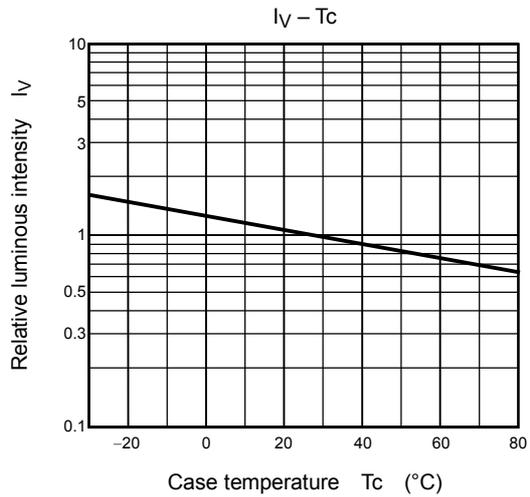
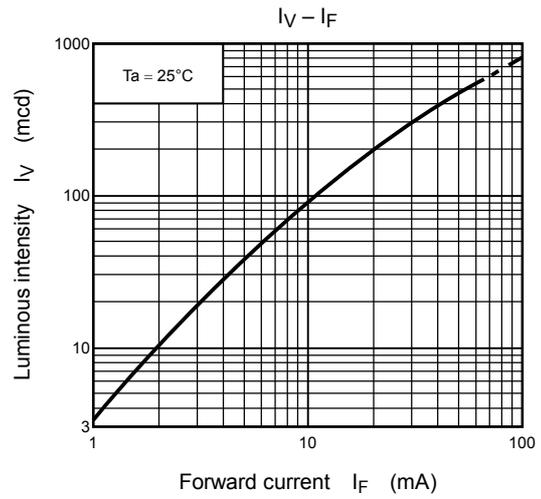
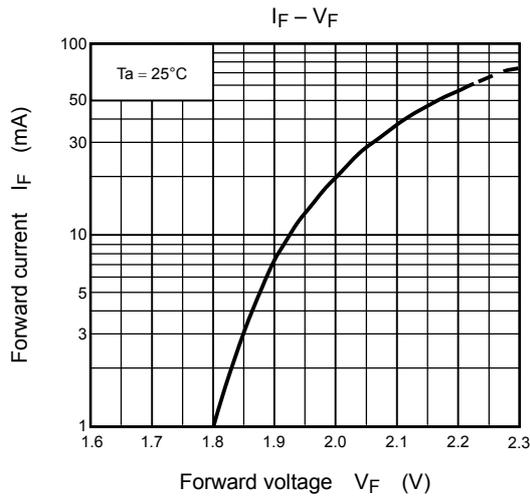
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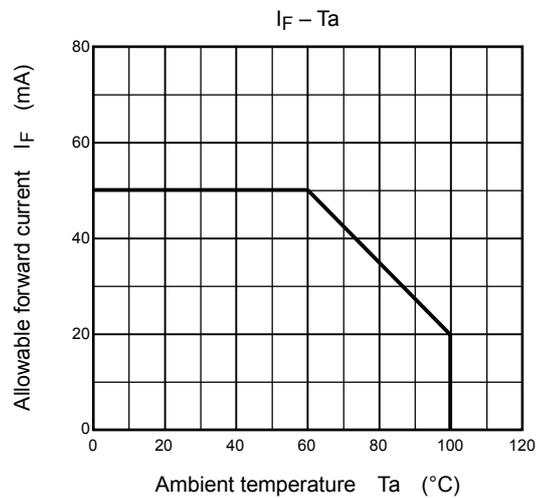
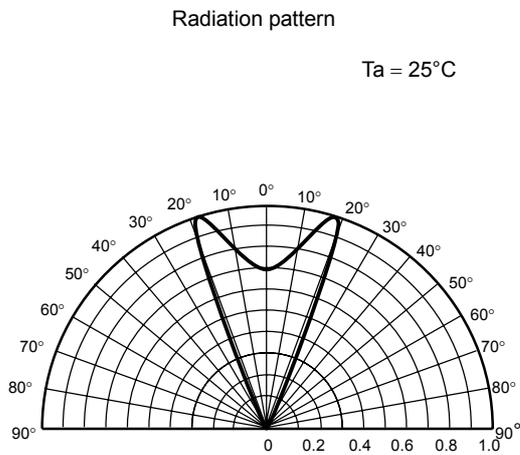
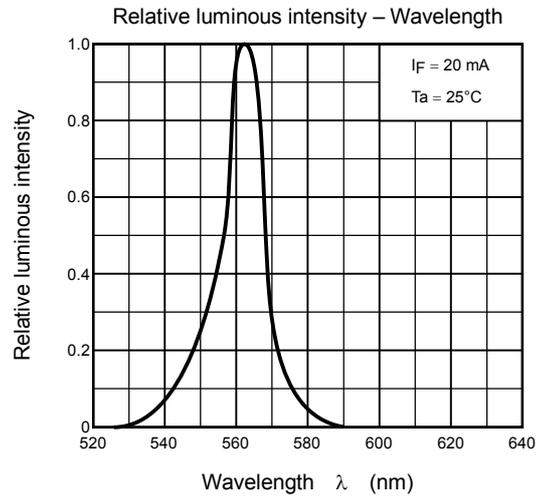
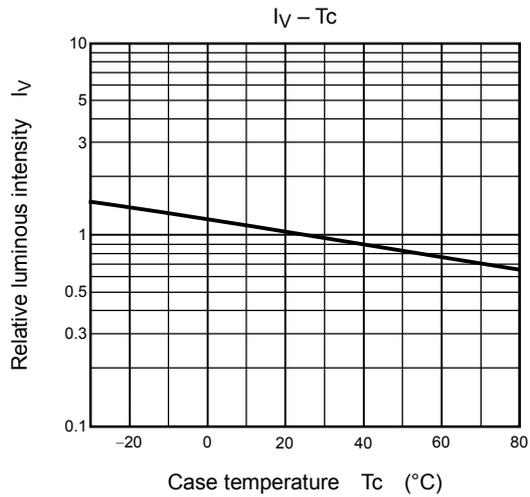
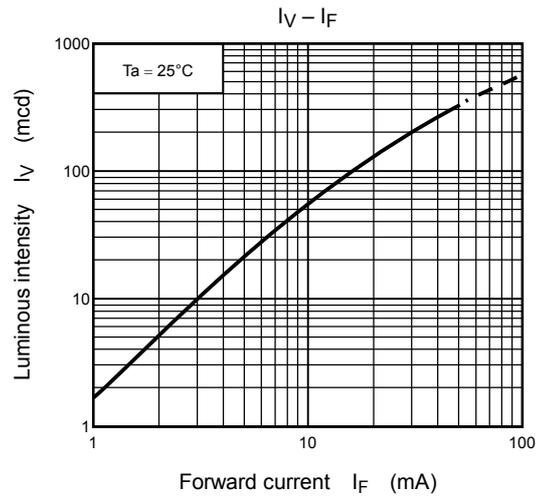
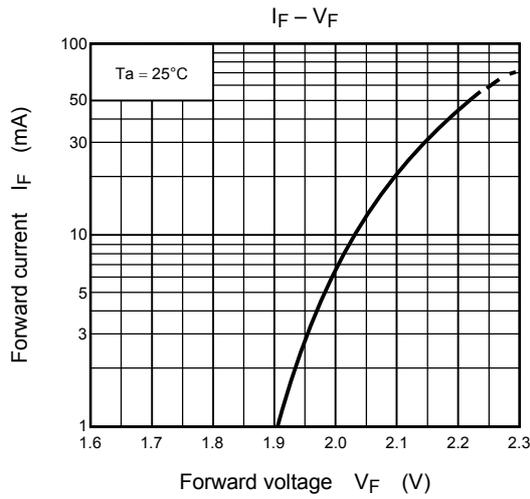
TLGE53T



TLFGE53T



TLPGE53T



RESTRICTIONS ON PRODUCT USE

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